Icemos Technology Ltd **Product Specification** **1003.661501** Issue Date 14 January 2020 09:4

Part Number Customer

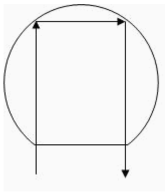
Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	{110}+/- 0.5 degree	Wafer Vendor
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	None or Semi Standard	
	5.0	Secondary Flat Length	18.00 +/- 2.00 mm	Wafer vendor
	6.0	Overall Thickness	500.00 +/- 12.00 µm	ADE, 100%
	7.0	Total Thickness Variation (TTV)	<5.00µm	Guaranteed by Process
	8.0	Bow	<20.00µm	ADE to ASTM F534, 20%
	9.0	Warp	<20.00µm	ADE to ASTM F657, 20%
	10.0	Edge Chips	0	Bright Light, 100% (note 2)
	11.0	Edge Exclusion	5mm	
	12.0	Edge Rounding	Round with STANDARD EDGE	IceMOS proprietary processing
HandleSilicon	13.0	Handle Growth Method	CZ	Wafer Vendor
	14.0	Handle Orientation	{100} +/- 0.5 degree	Wafer Vendor
	15.0	Handle Thickness	500.00 +/- 12.00 µm	ADE, 100%
	16.0	Handle Doping Type	P	Wafer Vendor
	17.0	Handle Dopant	Boron	Wafer Vendor
	18.0	Handle Resistivity	1 - 10 Ohmcm	Wafer Vendor
	19.0	Backside Finish	Polished with light handling marks. No lasermarking	Guaranteed by process
	20.0	Total LPD Count	<50.00pcs	@0.3um, Tencor 6220 particle counter
	21.0	Total scratch length	Front side <10mm total length	Bright Light, 100% (note 2)
	22.0	Surface Haze	none	Bright Light, 100% (note 2)

Part Number	Customer

Category	**Parameter**	**Specification**	**Measurement Method**
Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	

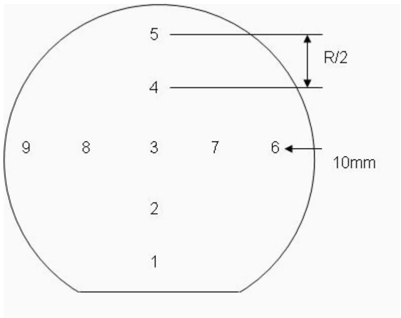
Explanatory Notes

1. Microscope inspection performed using microscope scan as below. 5x objective.



2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information